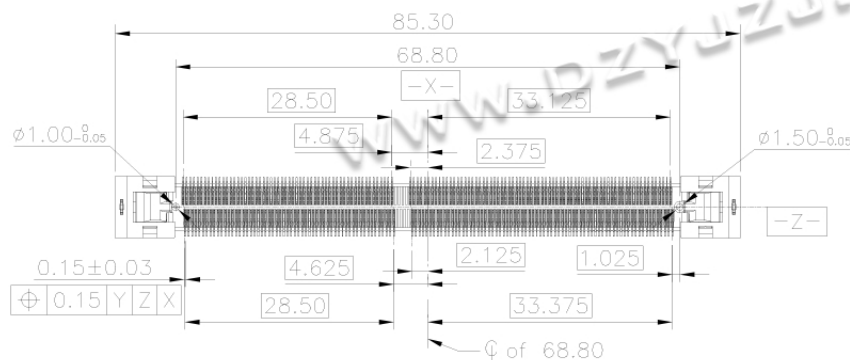
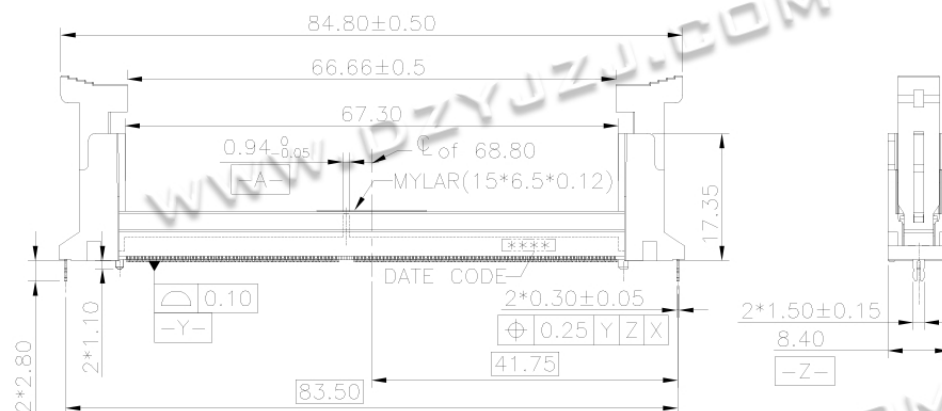
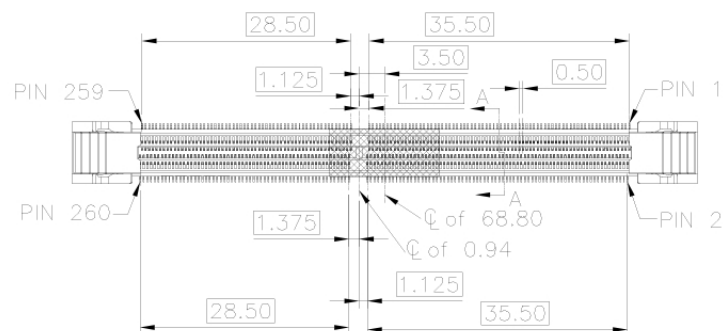




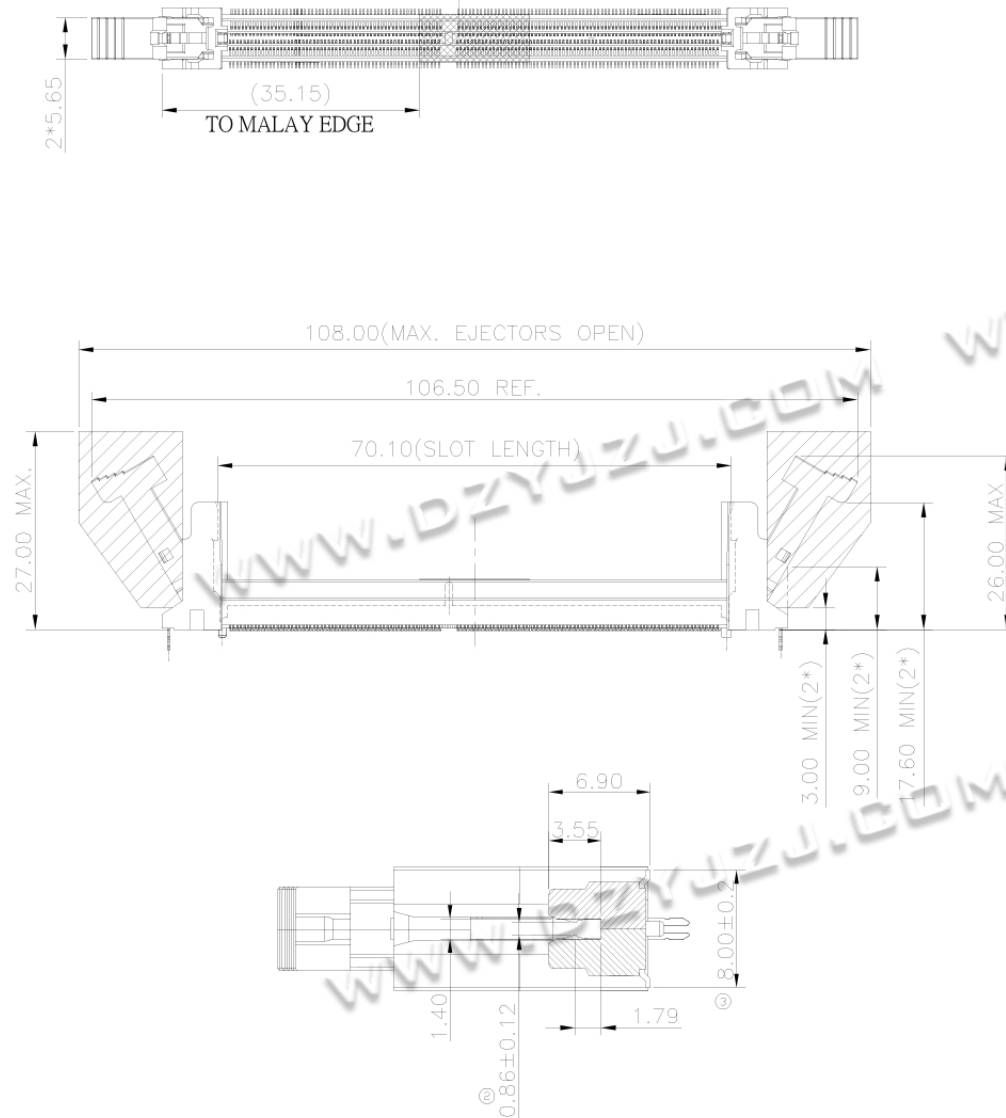
NOTES:

- MATERIAL SPECIFICATION:
 - HOUSING: LCP+40%GF,UL94V-0,COLOR: BLACK.
 - CONTACTS:COPPER_C7025,T=0.15mm;
 - HOOK: BRASS_C2680,T=0.30mm;
 - EJECTOR: HIGH TEMPERATURE THERMOPLASTIC, UL94V-0, COLOR: BLACK.
 - MYLAR: INSULATOR MATERIAL, COLOR: BROWN.
- PLATING SPECIFICATION:
 - CONTACT: NICKEL 50u" MIN. UNDER PLATING OVER ALL.MATTE TIN 100u" MIN. PLATING ON SOLDER AREA.GOLD PLATING SEE TABLE1.
 - HOOK: NICKEL 50u" MIN. UNDER PLATING OVER ALL. MATTE TIN 100u" MIN. PLATING OVER ALL.
- RoHS OR HF COMPLIANT;
- DATE CODE: ***
WEEK
YEAR
- MECHANICAL PERFORMANCE:
 - MATING FORCE: 11Kgf MAX..
 - DURABILITY: 25 CYCLES.
- ELECTRICAL PERFORMANCE:
 - CURRENT: 0.50A MAX. PER PIN.
 - VOLTAGE: 25V AC MAX..
 - LLCR: 55mΩ MAX. (INITIAL); Δ20mΩ MAX. (FINAL).
 - DIELECTRIC WITHSTANDING VOLTAGE: 250V AC FOR 1 MINUTE.
 - INSULATION RESISTANCE: DC 500V 500MΩ.
- RECOMMENDED PROCESS:
THE TEMPERATURE SHALL BE 260°C MAINTAINING 10 SECONDS.

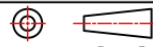


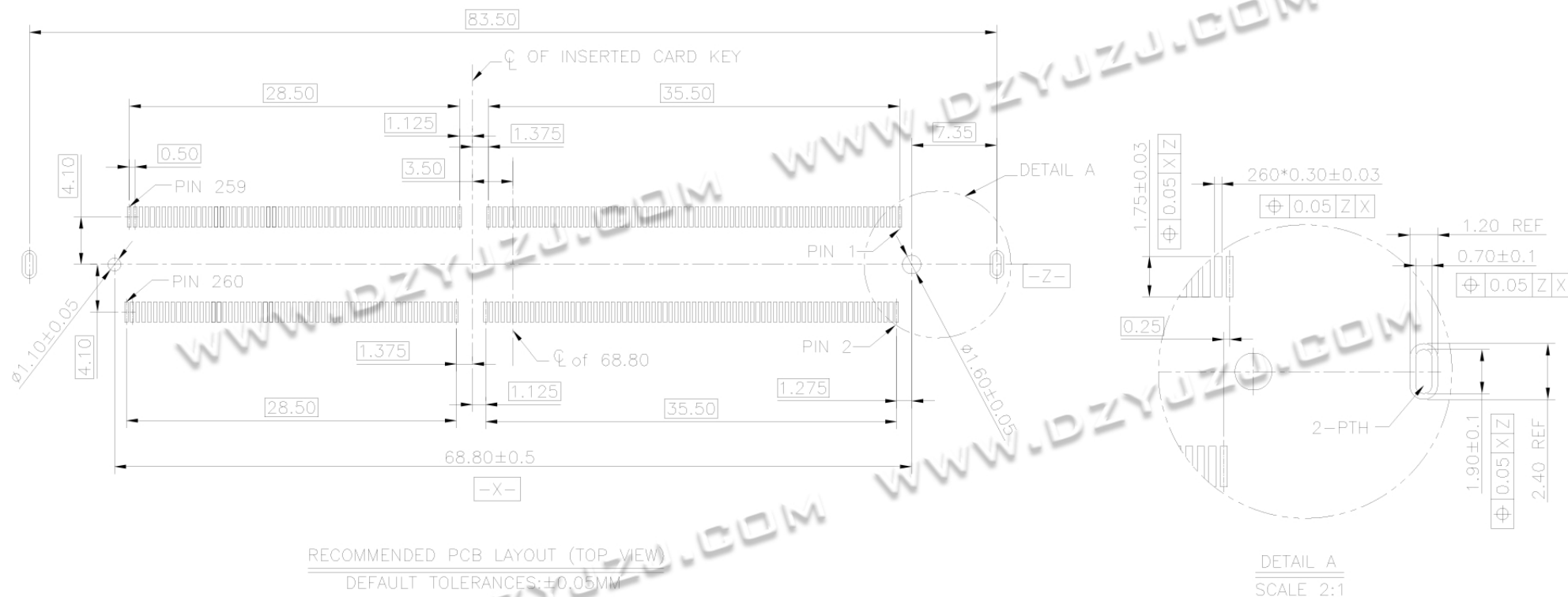
深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X." ±2" X.X" ±0.5'		DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: SODDR4 立贴	
 UNIT: mm [inch] SCALE:1:1 SIZE: A4		CHECKED BY: 马跃	DATE : 2014-02-23	PART NO.	HYC22-DDR4-254
		APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO.	
				DRAW NO:	HYC-2302271601
				SHEET NO.	1 OF 1



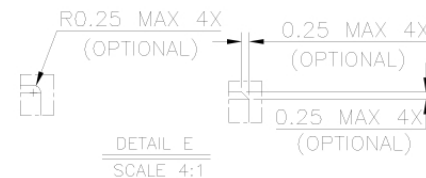
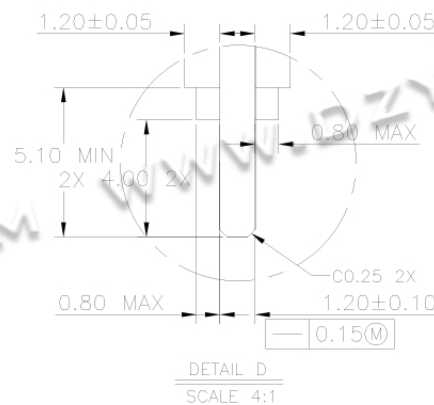
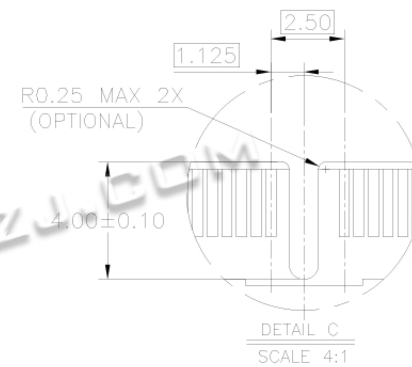
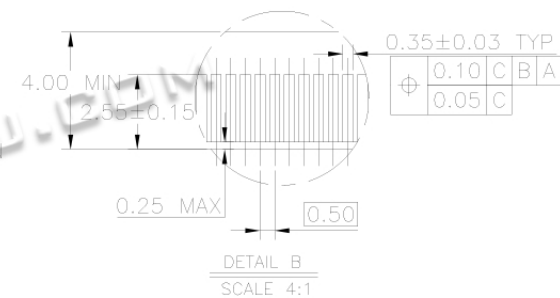
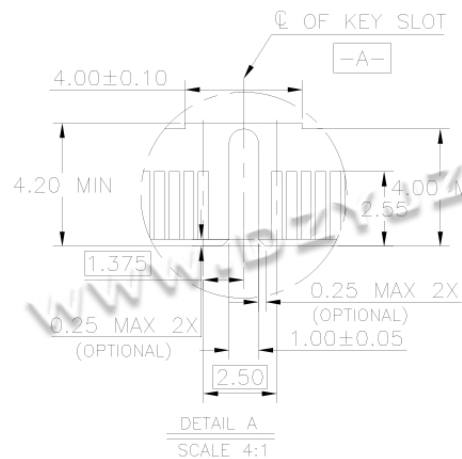
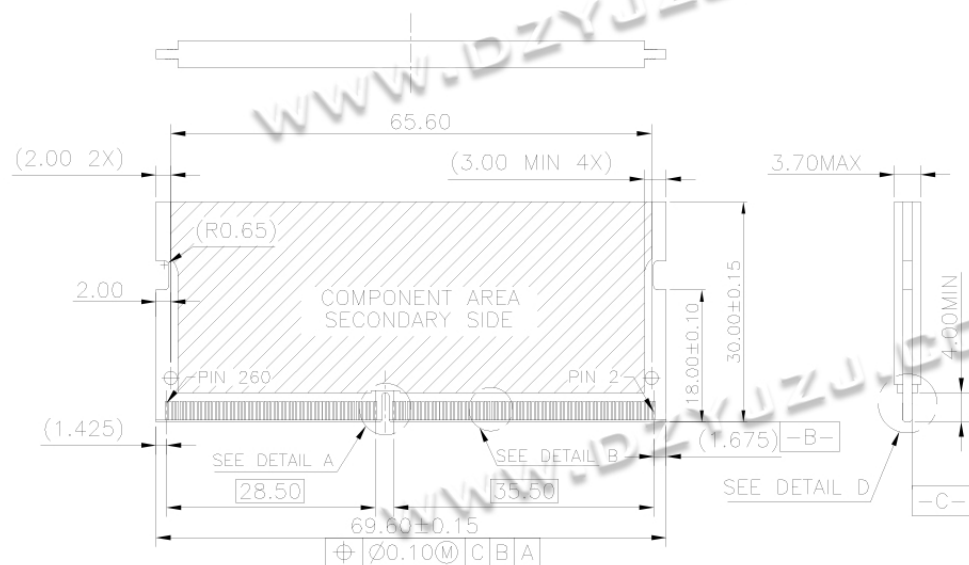
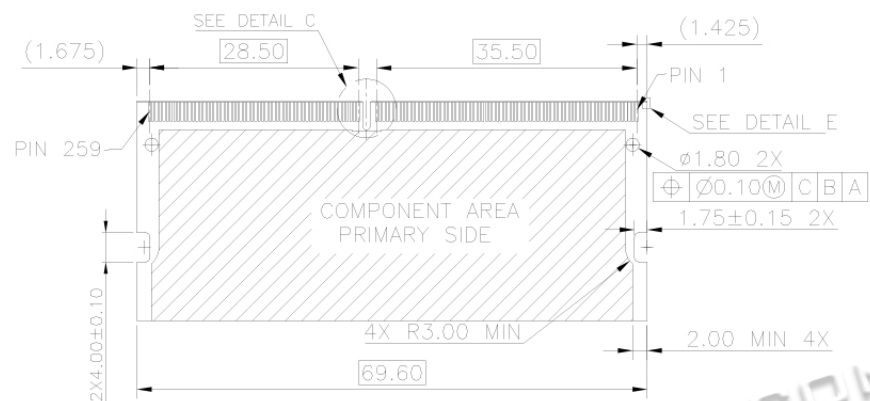
SECTION A-A
SCALE 2:1

 深圳市华宇创精密电子有限公司			
TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.* ±2* X.X* ±0.5*	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: SODDR4 立贴
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC22-DDR4-254
 UNIT: mm [inch] SCALE: 1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO. /
			DRAW NO: HYC-2302271601
			SHEET NO. 1 OF 1



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.* ±2* X.X* ±0.5*		DRAWN BY : 陈一鸣		DATE : 2014-02-23		PART NAME: SODDR4 立贴	
 UNIT: mm [inch]		CHECKED BY: 马跃		DATE : 2014-02-23		PART NO. HYC22-DDR4-254	
		APPROVED BY: 邱敏		DATE : 2014-02-23		MOLD NO. 	
SCALE:1:1 SIZE: A4				DRAW NO: HYC-2302271601		SHEET NO. 1 OF 1	



MATING P.C.B NOTES:

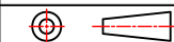
1. TOLERANCE ON ALL DIMENSIONS ± 0.05 UNLESS OTHERWISE SPECIFIED;
2. PCB THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALIZATION;
3. FINISH OF PAD: Au PLATING 30u"min OVER Ni PLATING 80u" MIN.;
4. NO BURR.
5. CHAMFER 0.25mm max. X 45° IF EXIST.



深圳市华宇创精密电子有限公司

TOLERANCE:

X.X ± 0.30
X.XX ± 0.25
X.XXX ± 0.15
X.* ± 2 X.X* ± 0.5



UNIT: mm [inch]

SCALE: 1:1 SIZE: A4

DRAWN BY :

陈一鸣

CHECKED BY :

马跃

APPROVED BY :

邱敏

DATE :

2014-02-23

DATE :

2014-02-23

DATE :

2014-02-23

PART NAME:

SODDR4 立贴

PART NO.

HYC22-DDR4-254

MOLD NO.

DRAW NO:

HYC-2302271601

SHEET NO.

1 OF 1